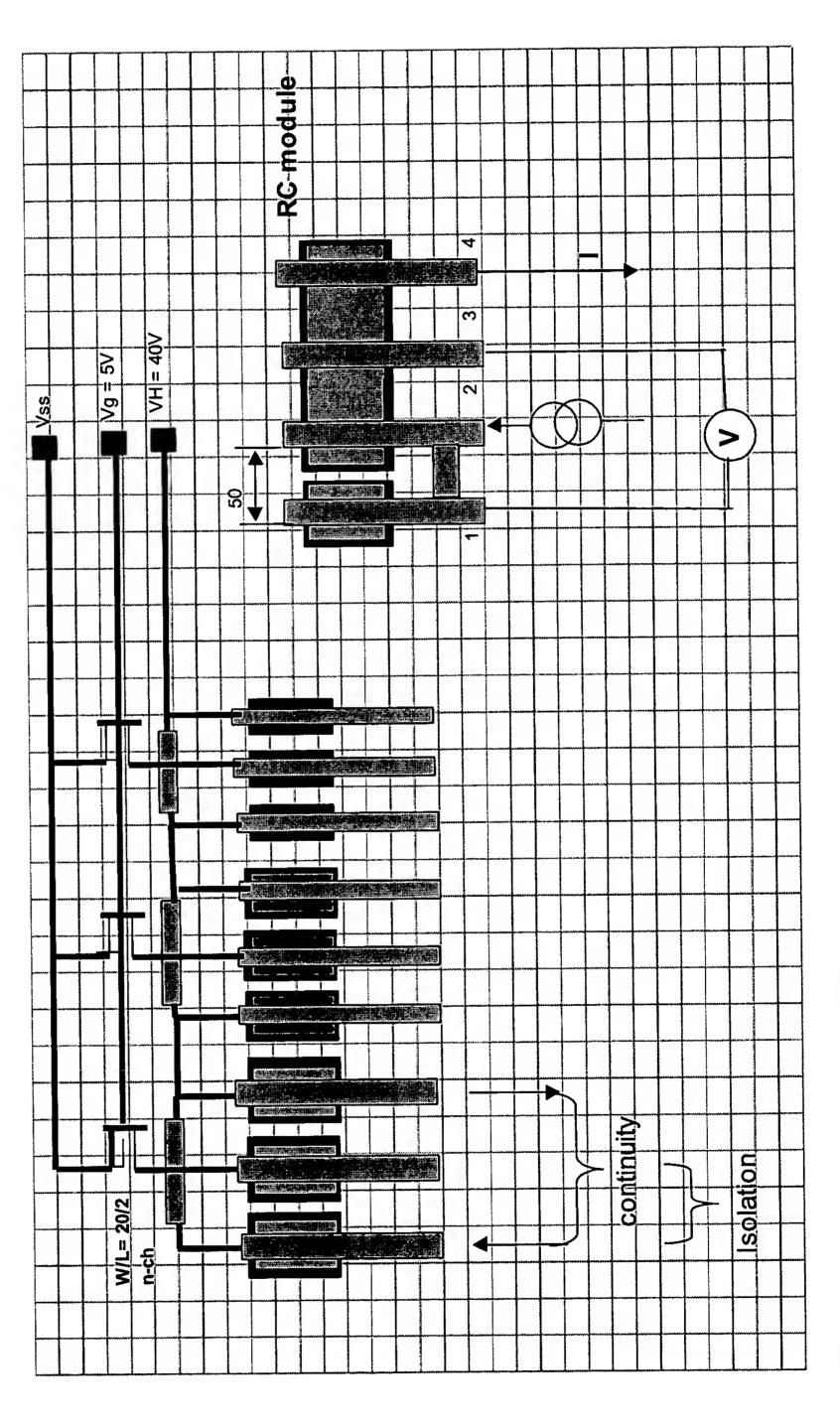
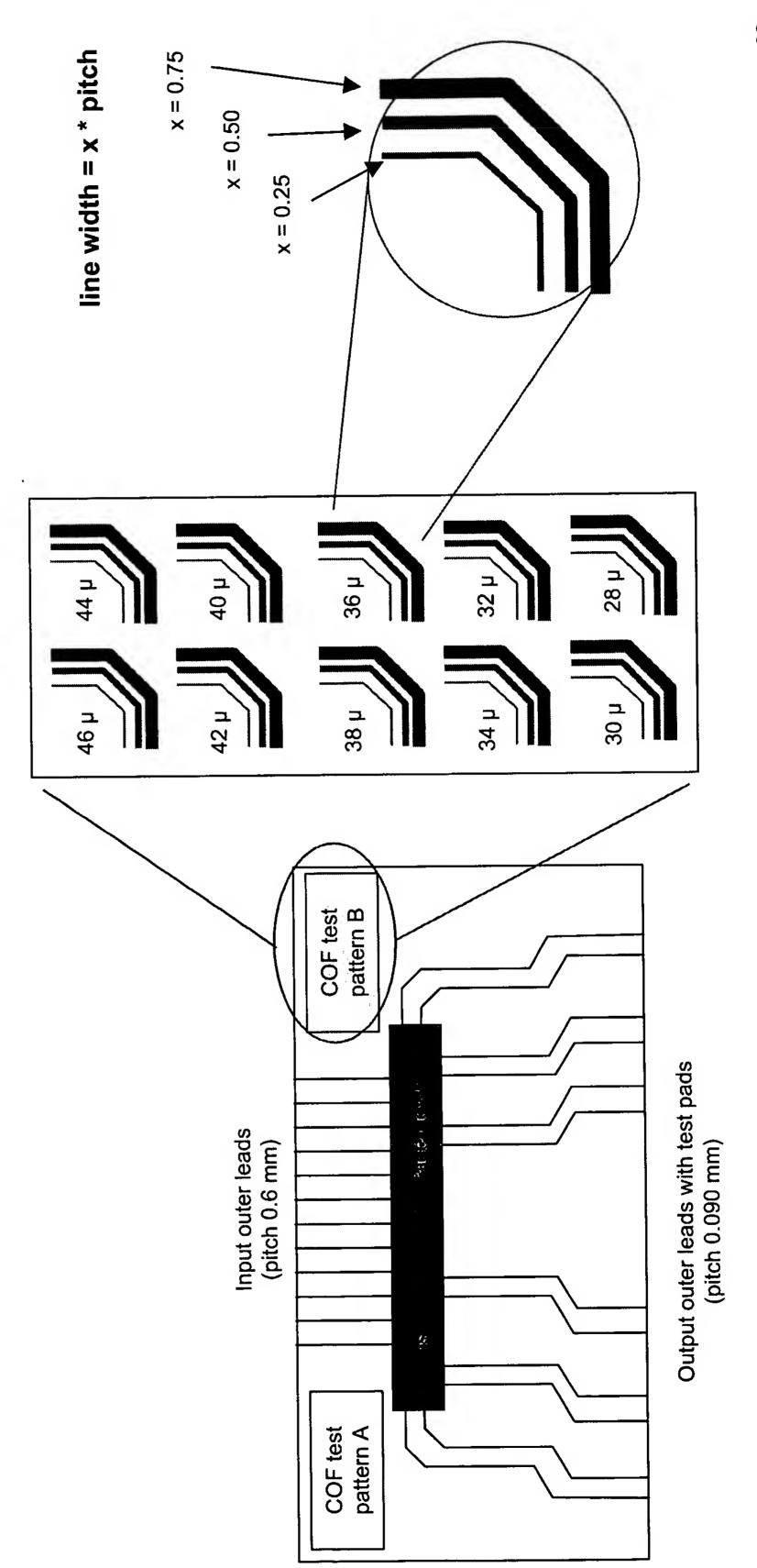
#### of test IC (2) Construction

- Test structures for isolation and continuity measurements
- Au and Al bumps



#### of test COF Construction

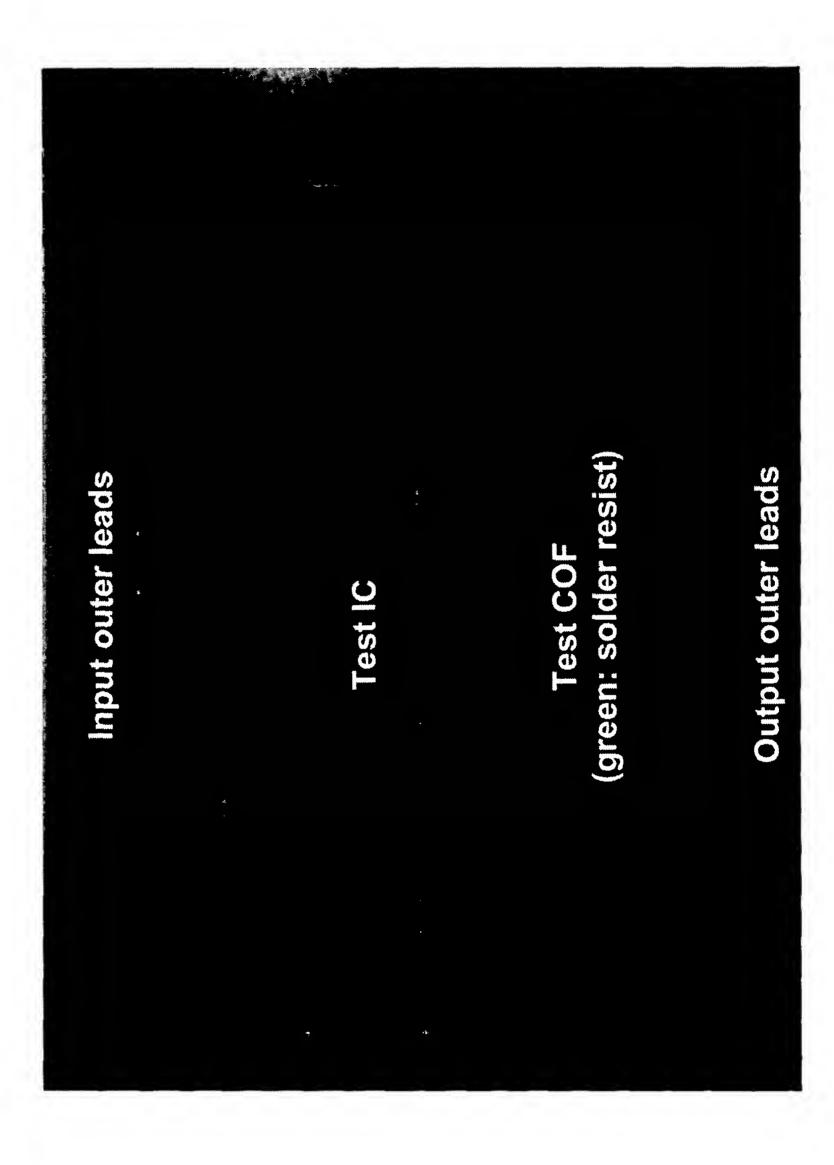
- Layout similar to existing COF products
- Additional test structures



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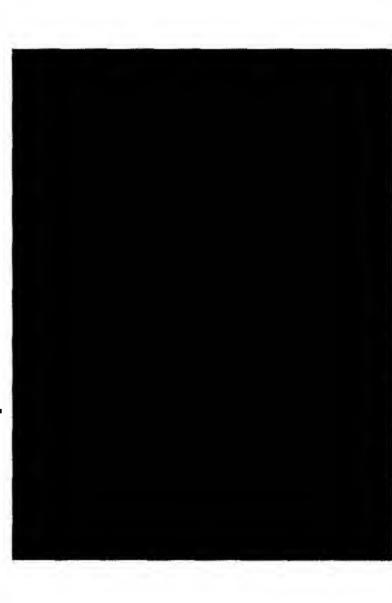
### Analysis of test COF (1) Construction

Overview (look through the tape onto die)

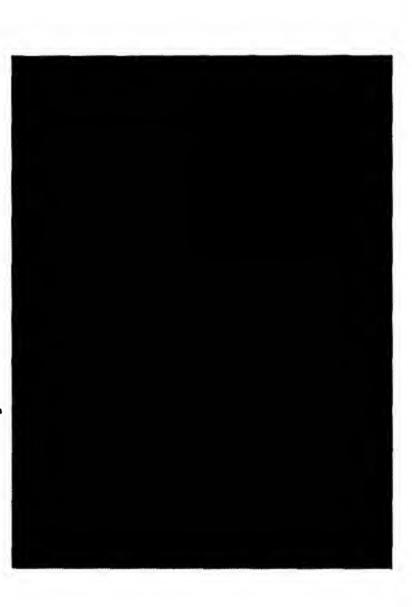


### Analysis of test COF (2) Construction

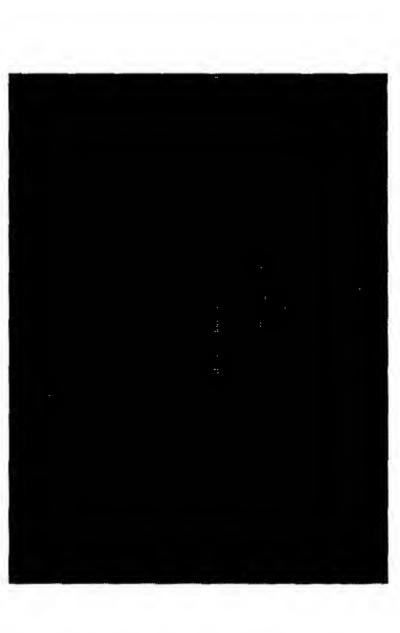
32 µm test structure



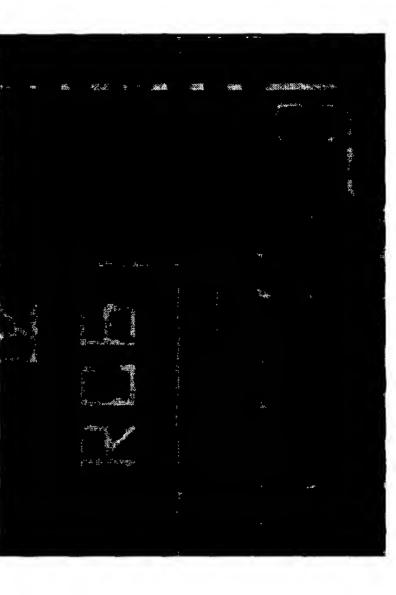
30 µm test structure



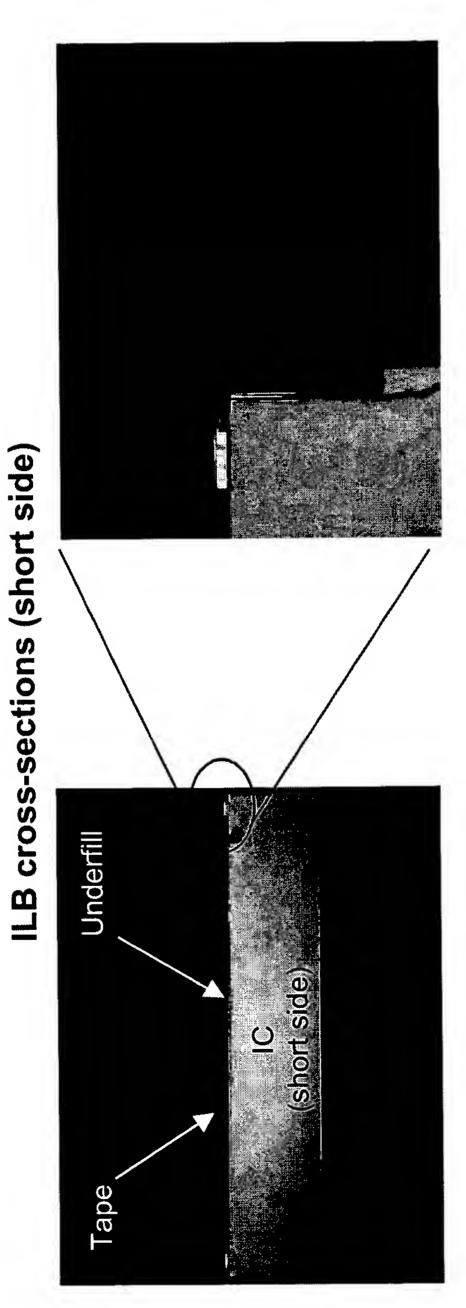
ILB at top left corner



ILB at bottom right corner



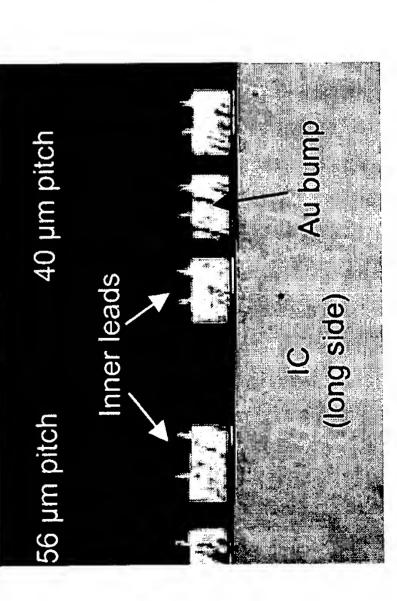


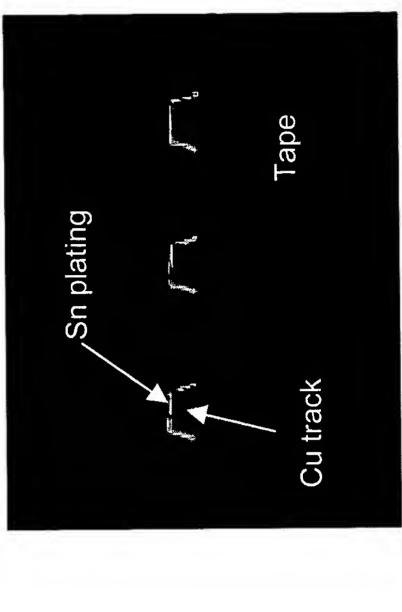


Tracks on COF tape (40 µm pitch)

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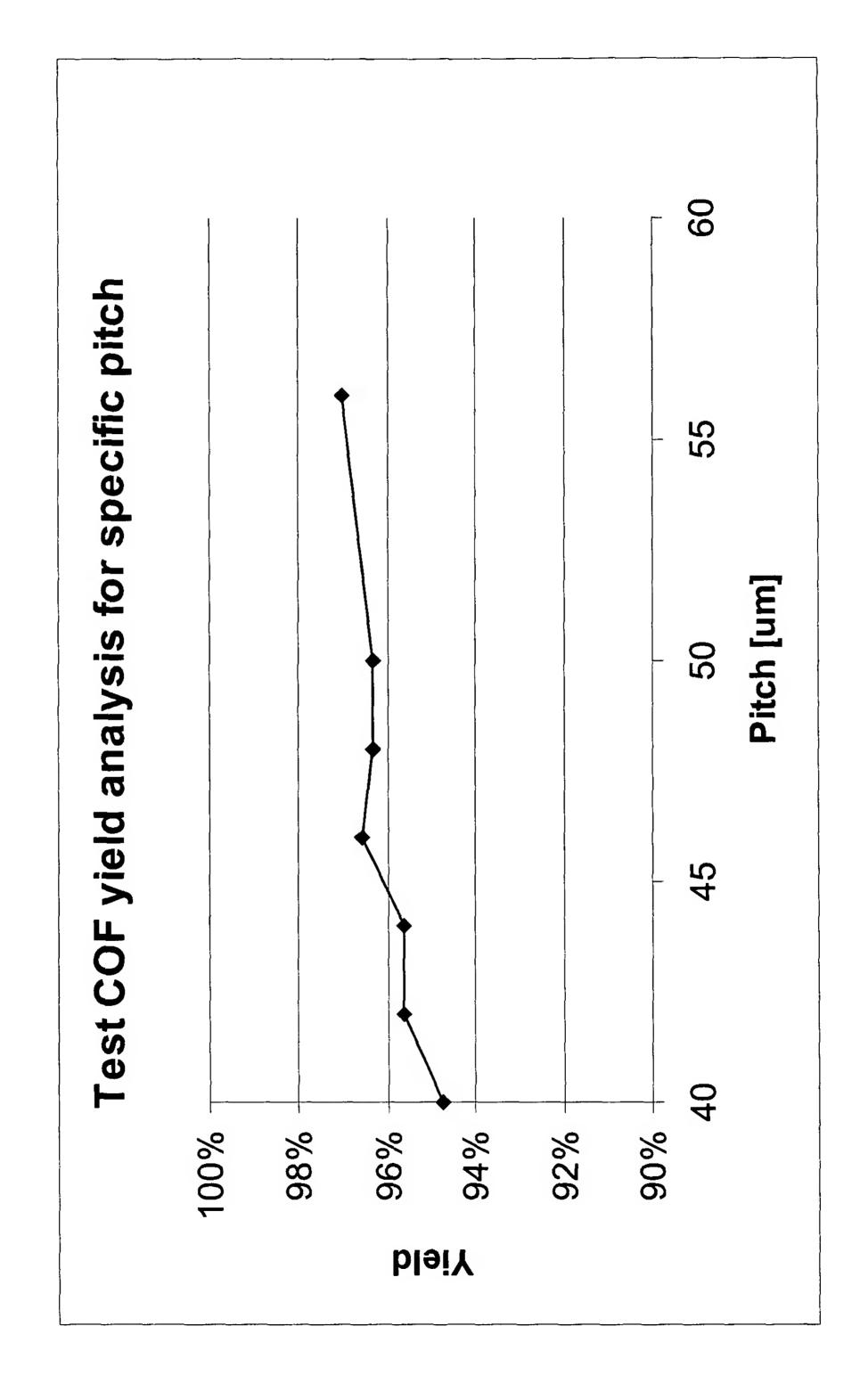
ILB cross-section (long sid



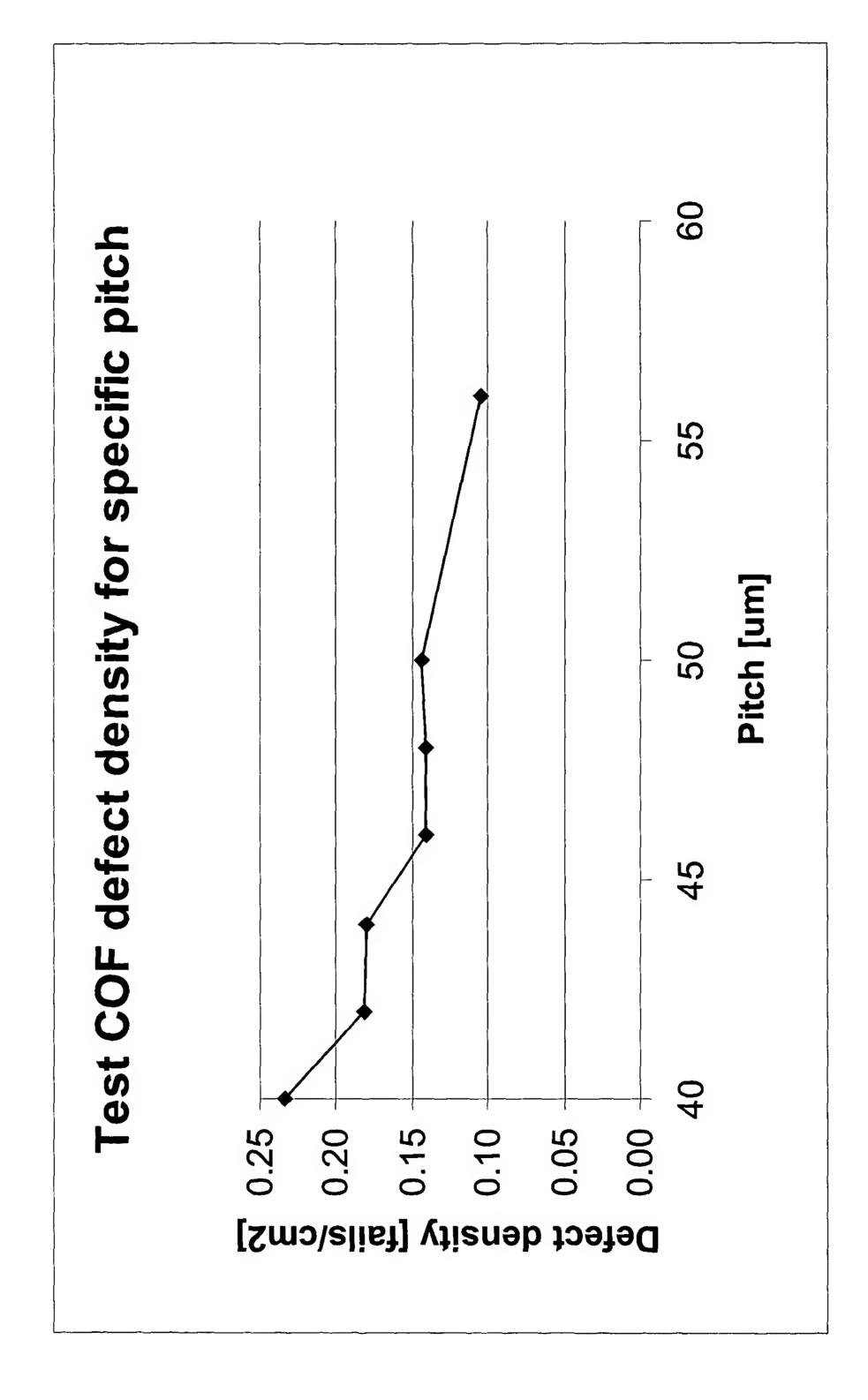


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### Yield analysis of test COF (1)



#### s of test COF (2) Yield analysi



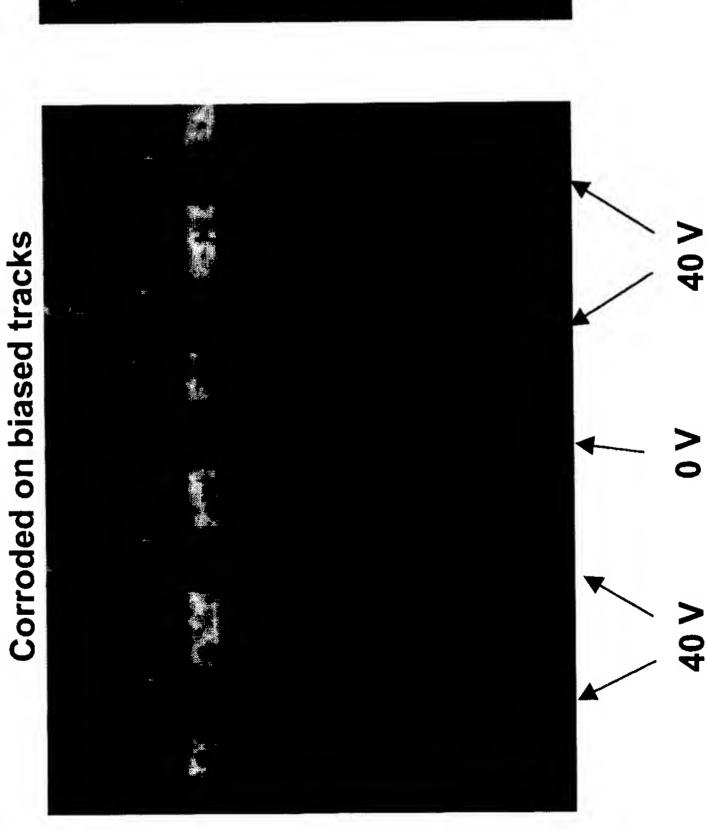
# Preliminary reliability test results (1)

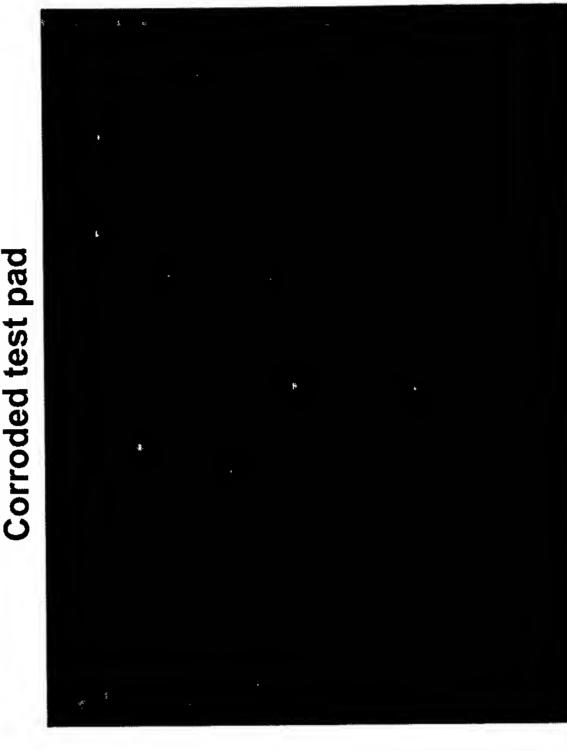
- Most of the standard reliability tests are pass:
- Temperature cycling (TMCL): -55°C, 125°C, 200 cycles
- celerated stress test (UHST): 125°C, 85% rH, 96 h Unbiased highly ac
- High temperature storage life (HTSL): 125°C, 1008 h

 Temperature humidity bias (THB), 85°C, 85% rH, 1008 h is fail for 25 V and 40 V bias.

# Preliminary reliability test results (2)

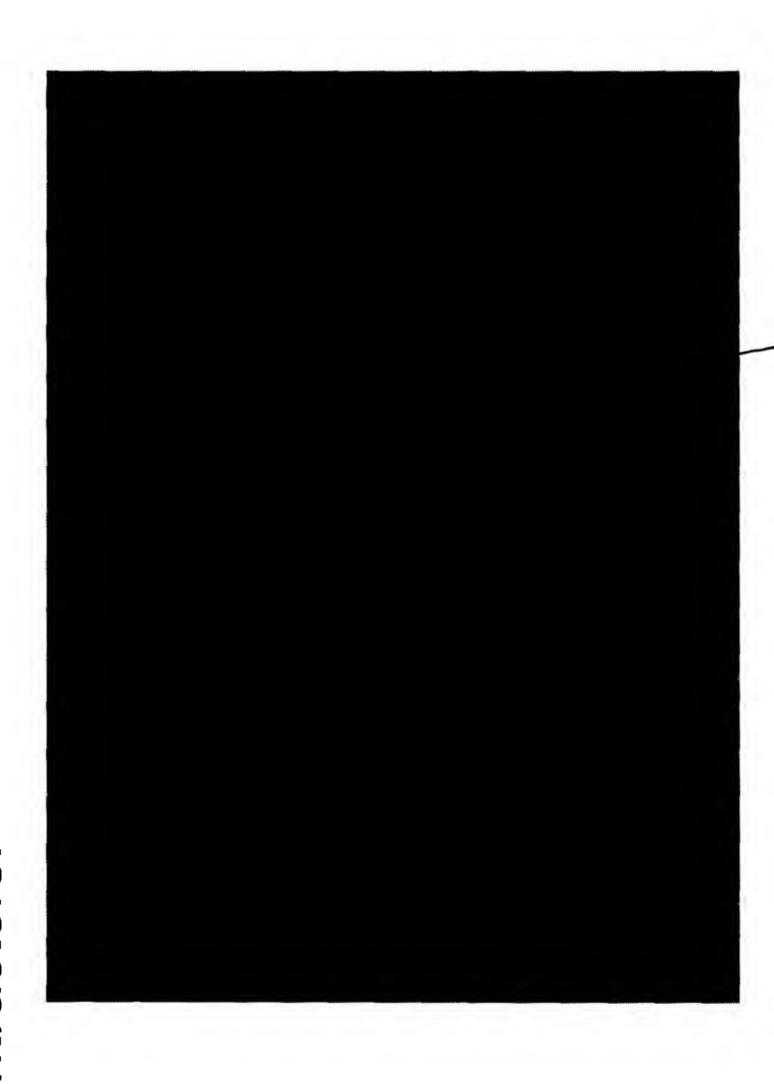
shows that corrosion and migration the lines where with a voltage difference was applied. A first investigation occurred between





## Preliminary reliability test results (3)

Further investigations are ongoing at Philips and at subcontractors.



"Tree-like" migration dendrites

#### Conclusions

COF is an interesting alternative for future display driver applications

The new concept seems to be a viable option to qualify new assembly processes

However, some reliability issues still need to be solved, namely the relationship between pitch and max. static bias voltage that can withstand 1008 h THB must be assessed.



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